

an encapsulant for encapsulating the lower metal sheets and the upper metal sheets, wherein the upper surfaces of the upper metal sheets are exposed from the encapsulant, and the lower surfaces of the lower metal sheets are exposed from the encapsulant and electrically connected to the printed circuit board.

5 2. The substrate structure according to claim 1, further comprising a middle board arranged among and flush with the upper metal sheets, and the integrated circuit package being mounted to the middle board.

3. The substrate structure according to claim 1, wherein the encapsulant is made of plastic material.

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ARGUMENTS

1. The examiner rejects claims 1,2,3,5 and 6 of the application.
2. Claims 5 and 6 have been canceled.
3. Claim 1-3 are rejected under 35 USC § 103(a) as being unpatentable over
15 admitted prior art FIG.1 and Spinelli (US4,472,762 et al).

Applicant thinks that admitted prior art FIG.1 and Spinelli (US4,472,762 et al. do not disclosed that a plurality of upper metal sheets are arranged on a plurality of lower metal sheets. An encapsulant is encapsulated the lower metal sheets and upper metal sheets, wherein the upper surface of the upper metal sheets
20 is exposed from the encapsulant, and the lower surface of the lower metal sheets is exposed from the encapsulated and electrically connected to the printed circuit board.

Then, according to the examiner's opinion, please refer to admitted prior art FIG.1. The substrate structure includes a plurality of metal sheets 10 arranged in
25 an array and an encapsulant 16.

Therefore, admitted prior art FIG.1 does not disclosed a similar structure to that of this application, and does not motivate the applicant to finish this